ABSTRUCT OF THE DISCLOSURE

Leakage current generated in a PN junction diode is reduced, and charge-up current caused by plasma treatment in formation of wiring connected to the PN junction diode is controlled. An N^{\dagger} region as a first conductive type impurity region provided in a Si substrate with an upper surface being exposed on one main surface of the Si substrate, a P^{\dagger} polysilicon plug provided with a bottom being contacted with an upper surface of the N^{\dagger} region, and wiring connected to a top of the P^{\dagger} polysilicon plug are included.